

2SA1791J

Silicon PNP epitaxial planar type

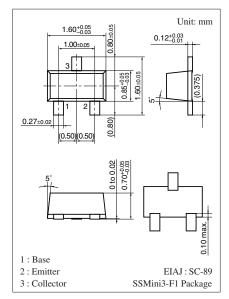
For high-frequency amplification Complementary to 2SC4656J

■ Features

- High transition frequency f_T
- \bullet Small collector output capacitance C_{ob}
- SS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing.

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	-50	V	
Collector-emitter voltage (Base open)	V _{CEO}	-50	V	
Emitter-base voltage (Collector open)	V_{EBO}	-5	V	
Collector current	I_C	-50	mA	
Collector power dissipation	P _C	125	mW	
Junction temperature	T_{j}	125	°C	
Storage temperature	T _{stg}	-55 to +125	°C	



Marking Symbol: AL

■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

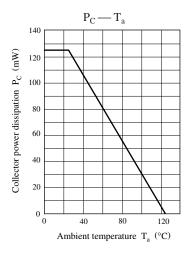
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_C = -10 \ \mu A, \ I_E = 0$	-50			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = -1 \text{ mA}, I_B = 0$	-50			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = -10 \ \mu A, I_C = 0$	-5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -10 \text{ V}, I_E = 0$			- 0.1	μΑ
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = -10 \text{ V}, I_B = 0$			-100	μΑ
Forward current transfer ratio *	h _{FE}	$V_{CE} = -10 \text{ V}, I_{C} = -2 \text{ mA}$	200		500	_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = -10 \text{ mA}, I_B = -1 \text{ mA}$		- 0.1	- 0.3	V
Transition frequency	f_T	$V_{CB} = -10 \text{ V}, I_E = 2 \text{ mA}, f = 200 \text{ MHz}$		250		MHz
Collector output capacitance	C _{ob}	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		1.5		pF
(Common base, input open circuited)						

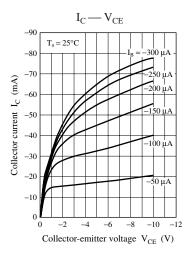
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

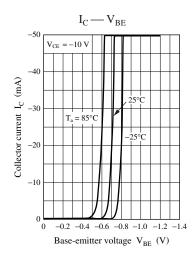
2. *: Rank classification

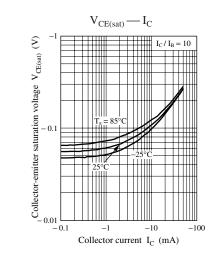
Rank	Q	R
h_{FE}	200 to 400	250 to 500

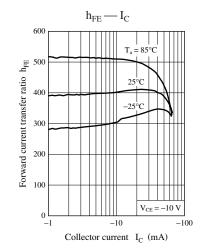
Panasonic

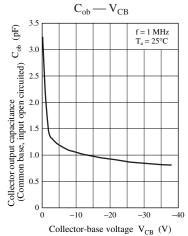












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